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(54) Title: APPARATUS AND METHOD FOR PLATING AND/OR POLISHING WAFER

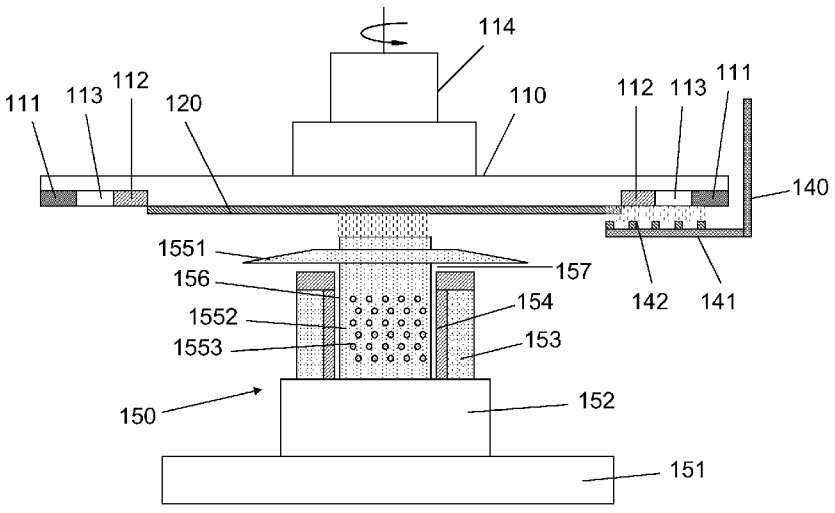


FIG. 1

(57) Abstract: An apparatus and a method for plating and/or polishing wafer. The apparatus includes a wafer chuck, an auxiliary nozzle apparatus(140, 240, 340) and a main nozzle apparatus (180, 208, 380). For plating and/or polishing the wafer,the wafer chuck holds and positions the wafer and horizontally moves and rotates. The auxiliary nozzle apparatus supplies uncharged or charged electrolyte to cover the outer edge of the wafer and the wafer chuck, he main nozzle apparatus supplies charged electrolyte to the surface of the wafer. The present invention can improve the plating and/or polishing uniformity of the outer edge of the wafer and reduce the entire electric resistance of the apparatus and improve the plating and/or polishing rate.

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